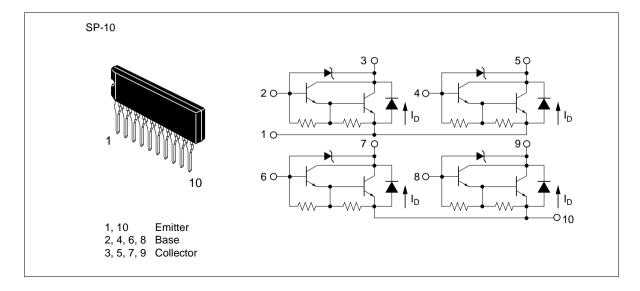
Silicon NPN Epitaxial

# HITACHI

#### Application

Low frequency power amplifier

#### Outline





#### **Absolute Maximum Ratings** (for each device, $Ta = 25^{\circ}C$ )

Item	Symbol	Ratings	Unit	
Collector to base voltage	V <sub>CBO</sub>	27	V	
Collector to emitter voltage	V <sub>CEO</sub>	27	V	
Emitter to base voltage	V <sub>EBO</sub>	7	V	
Collector current	Ι <sub>c</sub>	2	А	
Collector peak current	I <sub>C(peak)</sub>	4	А	
Diode current	I <sub>D</sub>	2	А	
Collector power dissipation	<b>P</b> <sub>c</sub> * <sup>1</sup>	4	W	
	$P_{c}^{*1} (T_{c} = 25^{\circ}C)$	28		
Junction temperature	Tj	150	٥C	
Storage temperature	Tstg	-55 to +150	°C	

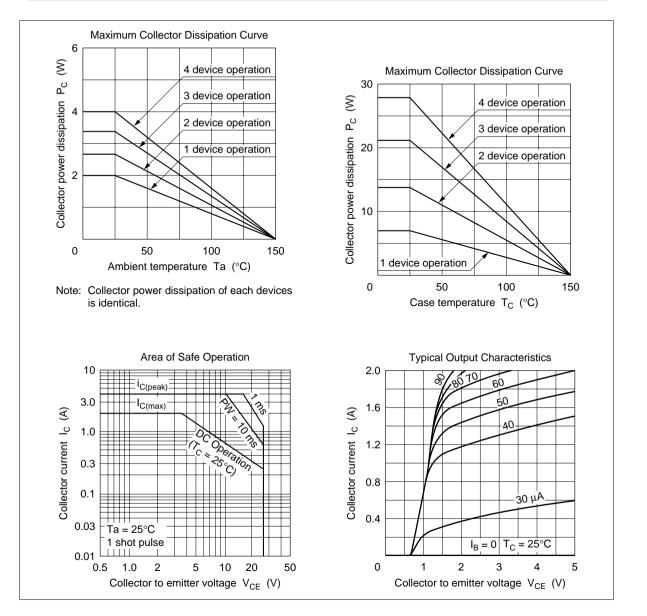
Note: 1. 4 devices operation.

#### **Electrical Characteristics** (for each device, $Ta = 25^{\circ}C$ )

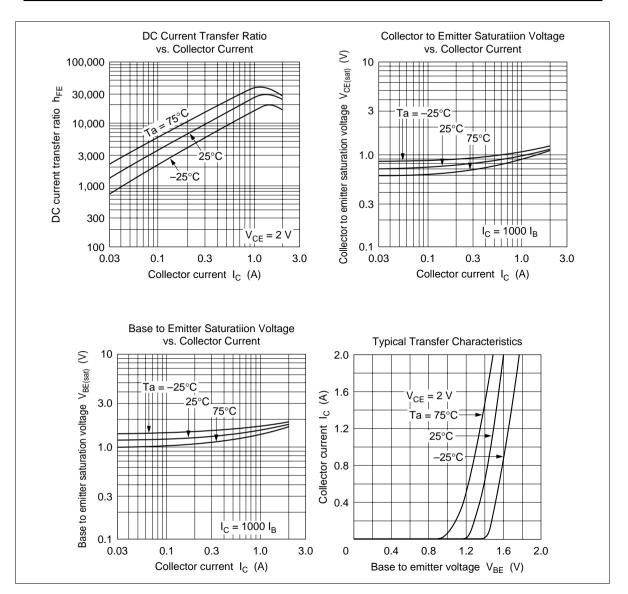
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to emitter breakdown voltage	$V_{(BR)CBO}$	27	_	—	V	$I_{c} = 1 \text{ mA}, I_{E} = 0$
Collector to emitter sustain voltage	$V_{\text{CEO}(\text{SUS})}$	28	_	36	V	$I_{c}$ = 1 A, L = 20 mH, $R_{BE}$ = $\infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	7	—	—	V	$I_{\rm E} = 5  {\rm mA},  I_{\rm C} = 0$
Collector cutoff current	I <sub>CBO</sub>	_	_	10	μΑ	$V_{CB} = 20 \text{ V}, \text{ I}_{E} = 0$
	I <sub>CEO</sub>	—	—	10	_	$V_{ce}$ = 20 V, $R_{be}$ = $\infty$
DC current transfer ratio	$h_{\text{FE}}$	7000	—	30000		$V_{ce} = 2 \text{ V}, \text{ I}_{c} = 0.5 \text{ A}$
	h <sub>FE</sub>	2000	—	—	_	$V_{ce} = 2 V, I_c = 2 A^{*1}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	—	_	1.5	V	$I_{c} = 2 \text{ A}, I_{B} = 2 \text{ mA}^{*1}$
Base to emitter saturation voltage	$V_{BE(sat)}$	—	—	2.0	V	$I_{c} = 2 \text{ A}, I_{B} = 2 \text{ mA}^{*1}$
C to E diode forward current	V <sub>D</sub>	_	_	3.5	V	I <sub>D</sub> = 2 A
Note: 1 Pulse test						

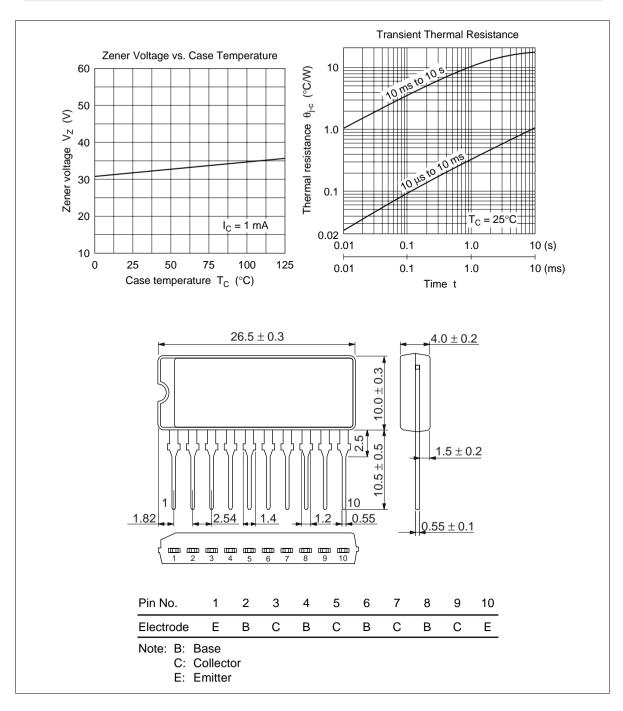
Note: 1. Pulse test.

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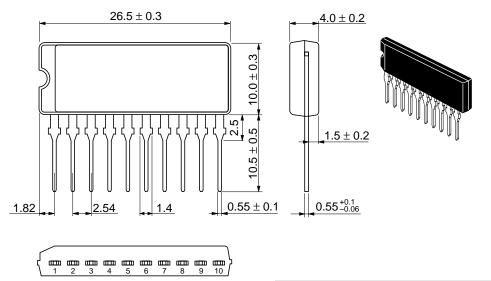
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#### Unit: mm



Hitachi Code	SP-10
JEDEC	—
EIAJ	—
Weight (reference value)	2.9 g

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